

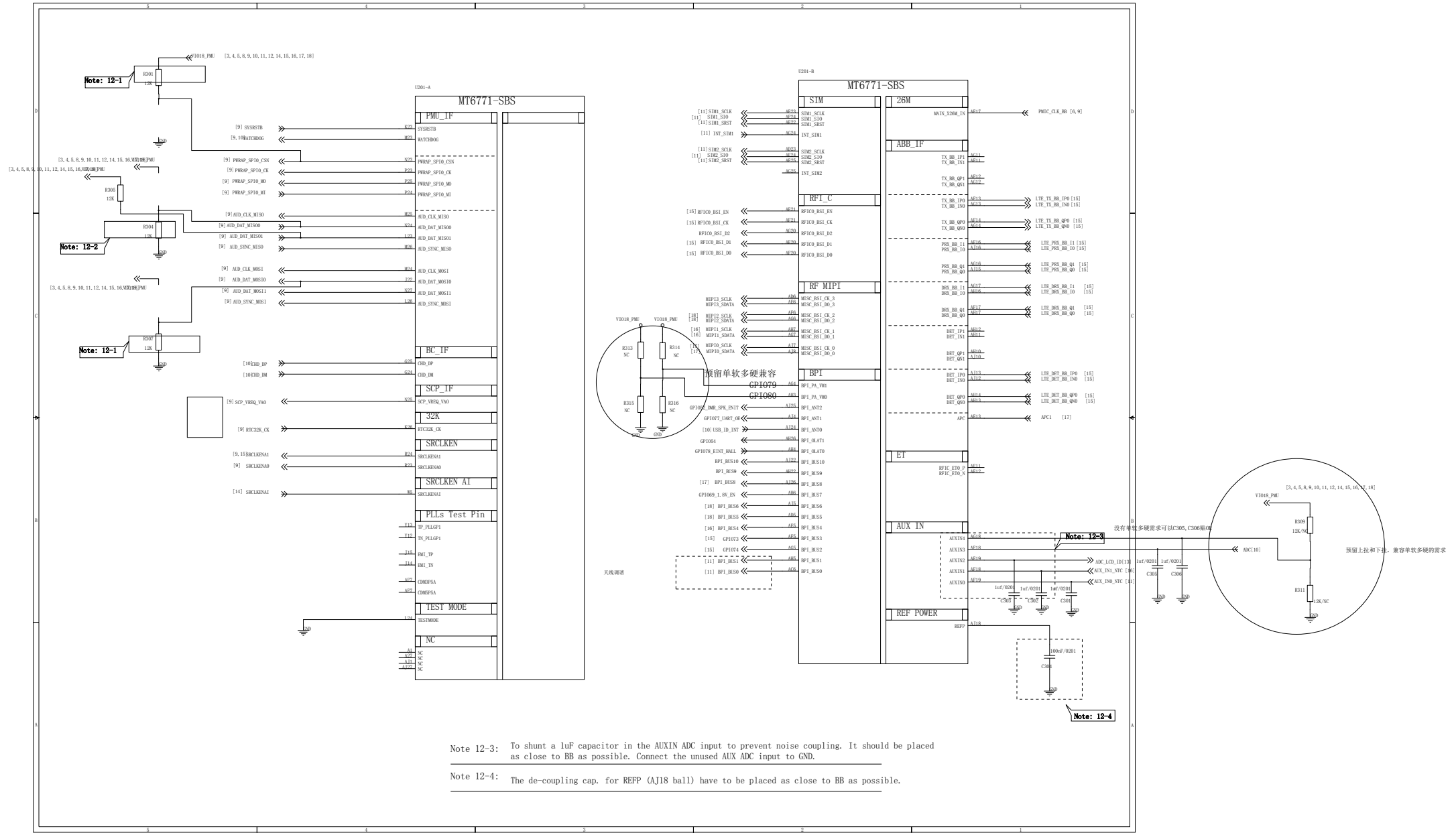
Note 12-1: "PWRAP_SPI0_CSN" and "AUD_DAT_MOSIO" are bootstrap pin to select which interface will be the JTAG pin out.

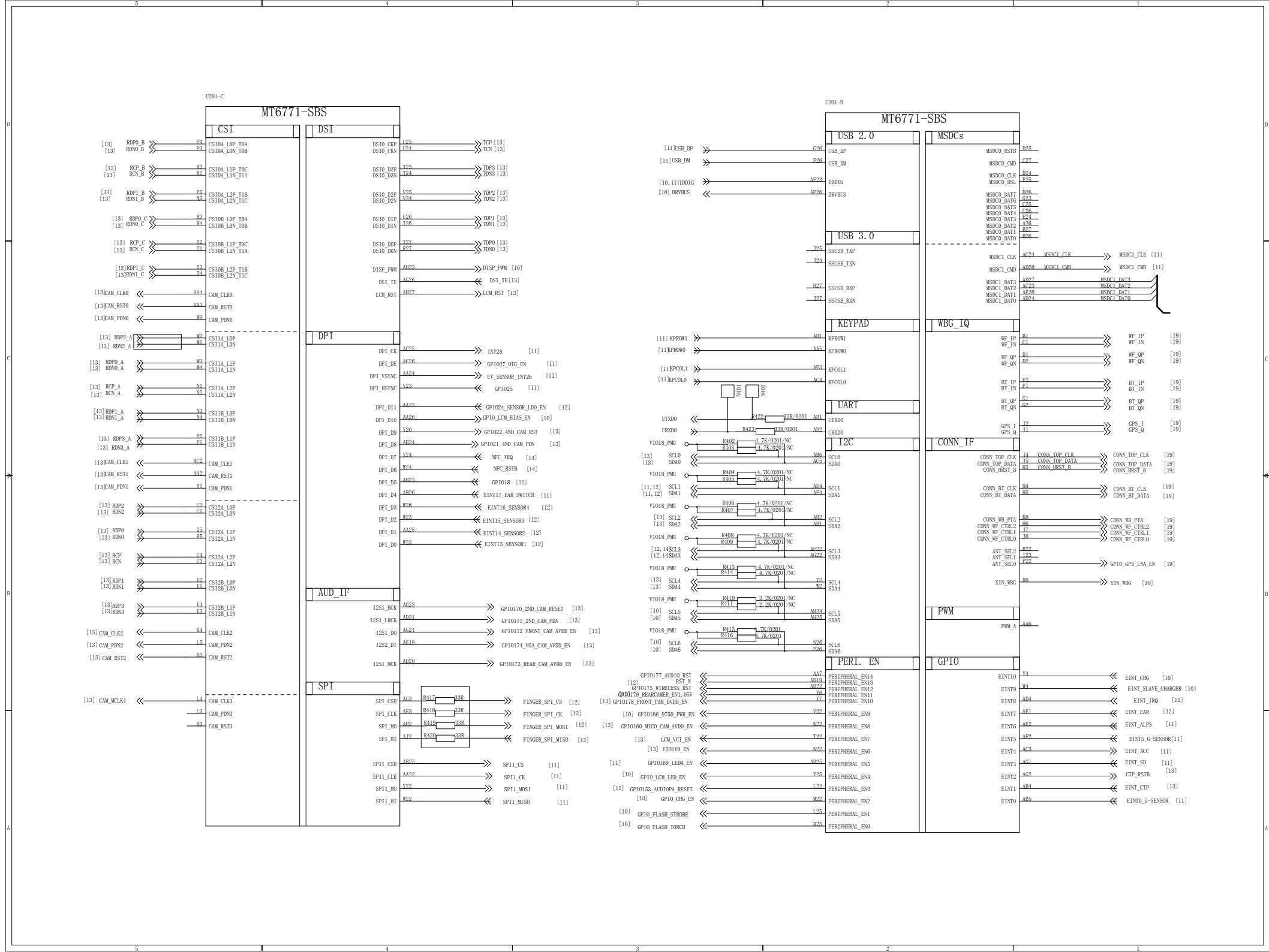
PWRAP_SPI0_CSN	AUD_DAT_MOSIO	Which interface will be the JTAG pin out	
		AP_JTAG	IO_JTAG
HI	LO	N/A	N/A
HI	HI	SPI_CSB/SPI_CLK/ SPI_M0/SPI_M1 / EINT8	DPI_11/DPI_HSINC/DPI_VSYNC /DPI_DE/DPI_CLK/DPI_D8/DPI_D9
LO	LO	SPI_CSB/SPI_CLK/ SPI_M0/SPI_M1 / EINT8	N/A
LO	HI	MSDC1_CLK/CMD/ DAT0/DAT1/DAT2	N/A

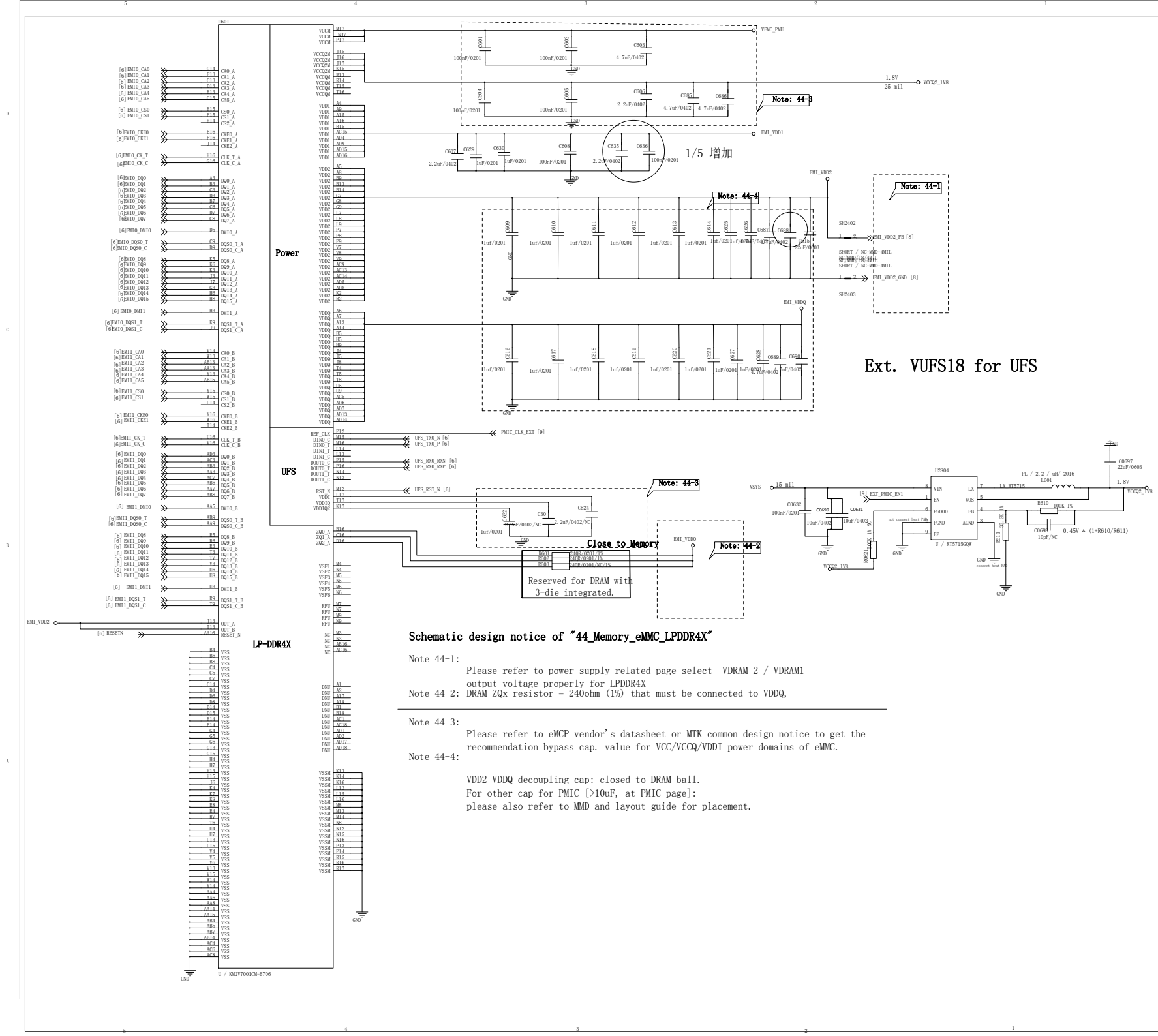
Note 12-2: "AUD_DAT_MISO0" is bootstrap pin to enable serial JTAG output over USB2.0 interface or not.
When "AUD_DAT_MISO0" is pulled to high in system start up and then USB2.0 interface will be switched into serial JTAG mode.

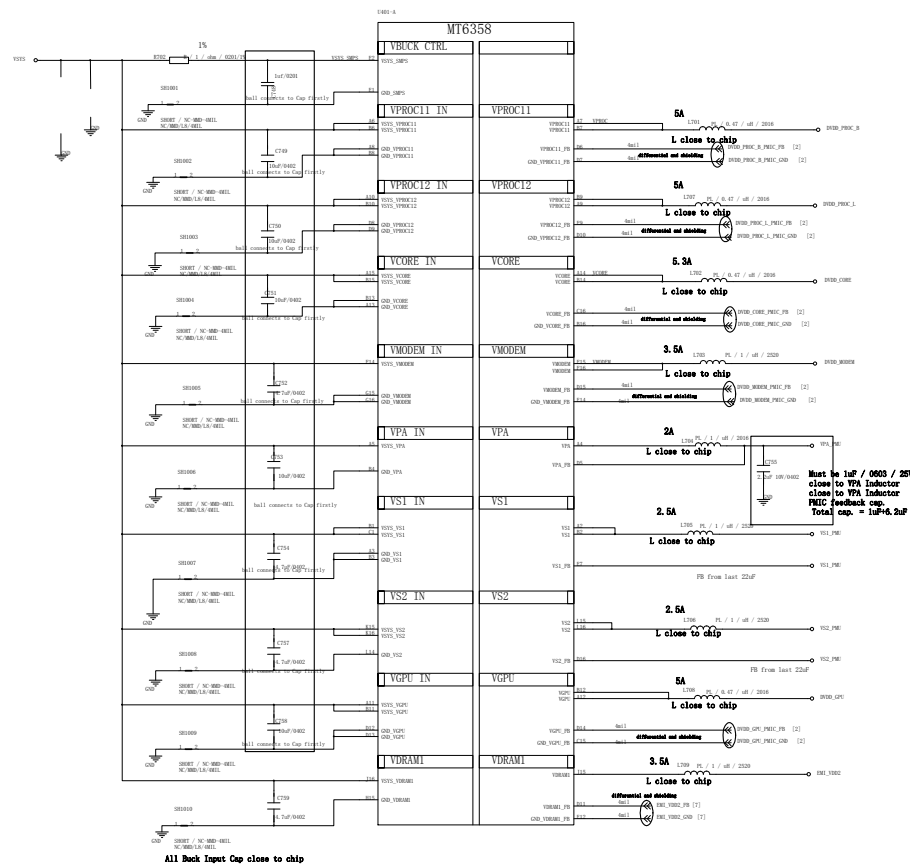
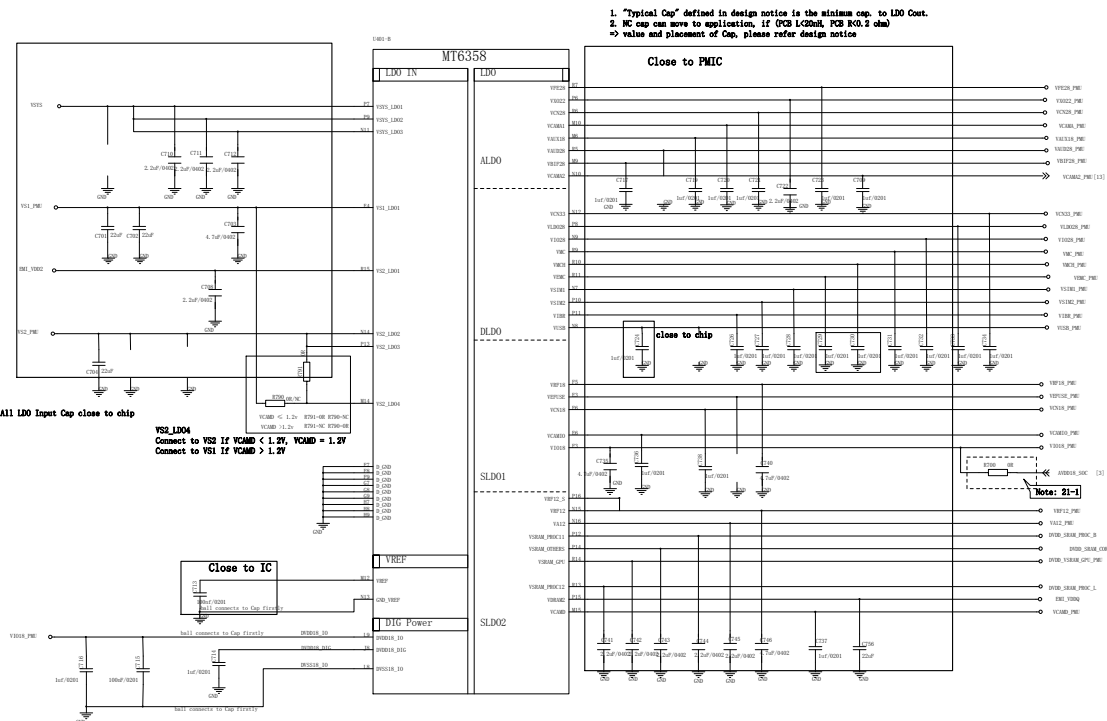
"AUD_DAT_MISO1" is bootstrap pin to select system booting up from eMMC or UFS device.

AUD_DAT_MISO1	Booting device
LO	eMMC
HI	UFS



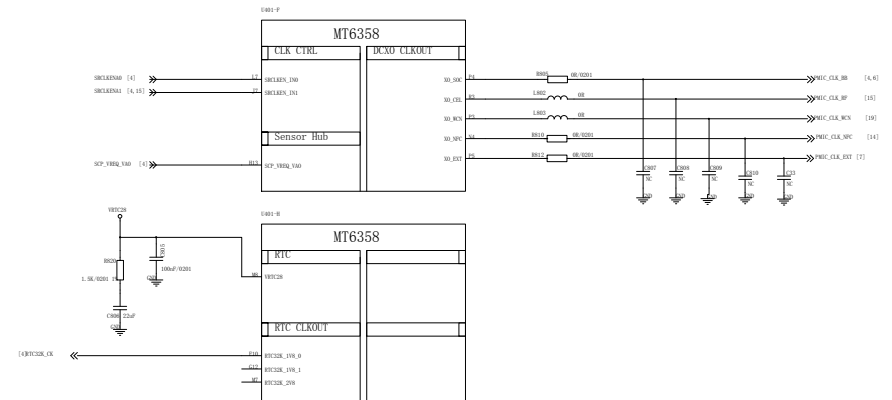
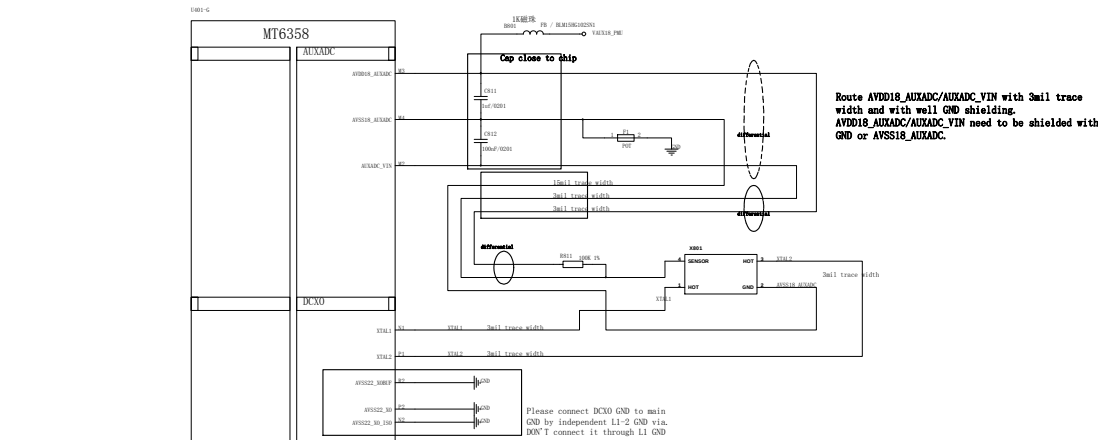
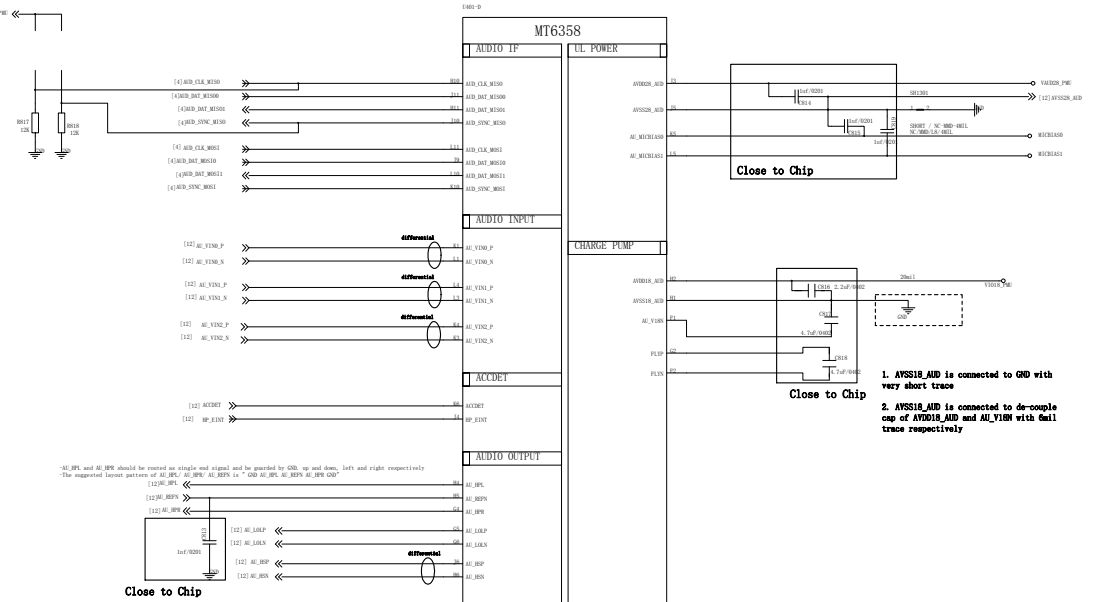
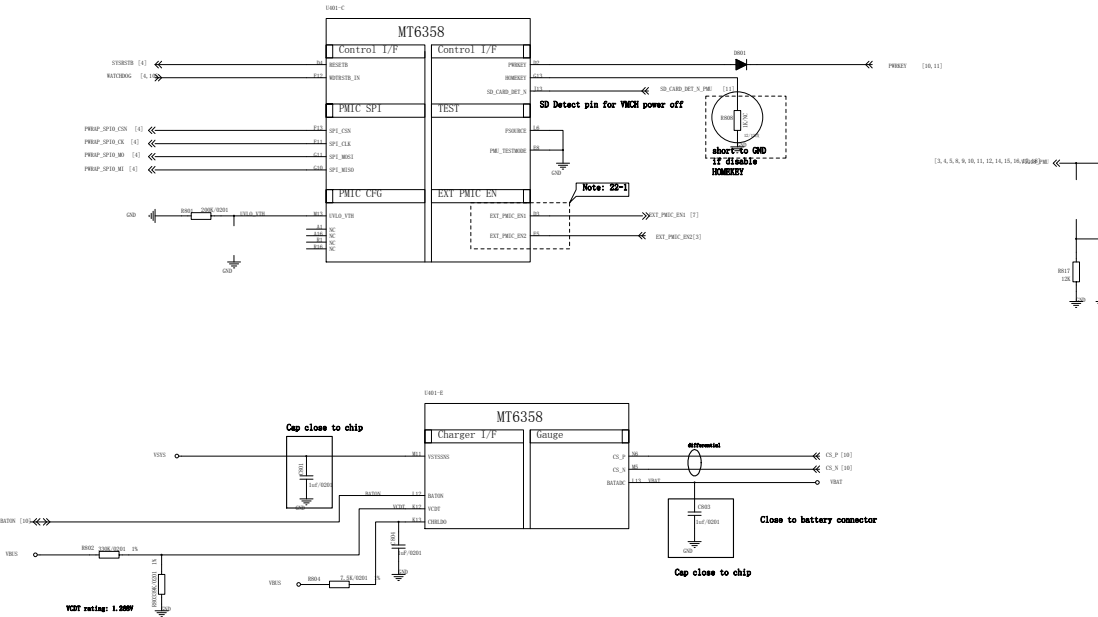






Note 23-1: VDRAM 2 / VDRAM1 output voltage vs. trap pin.

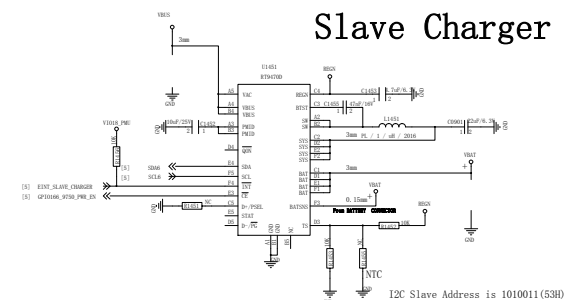
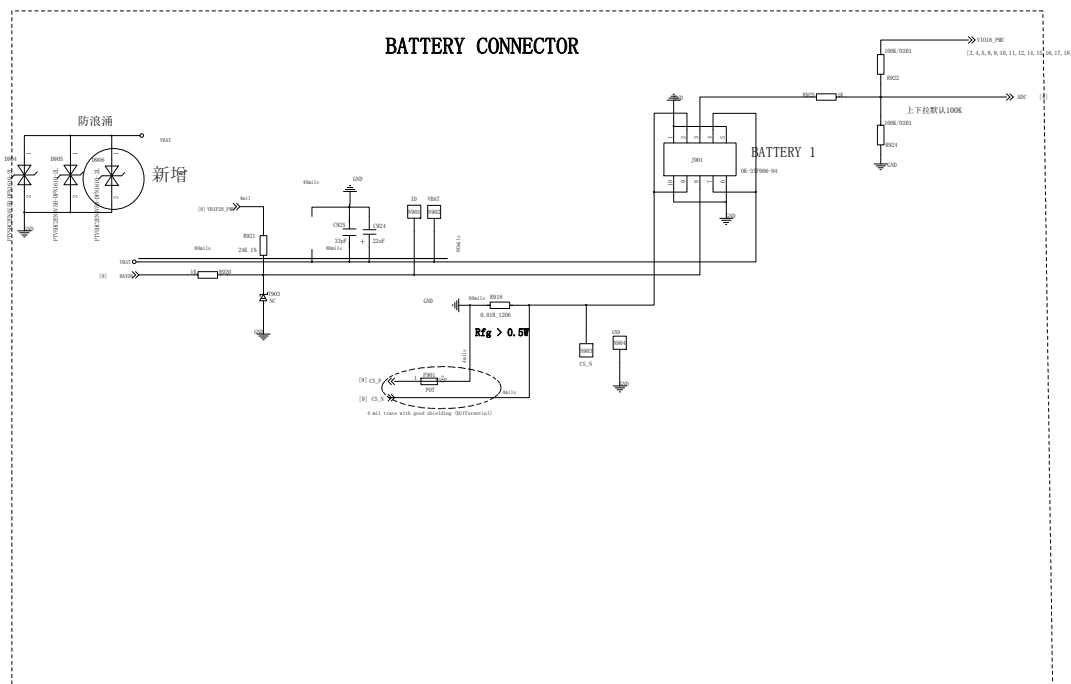
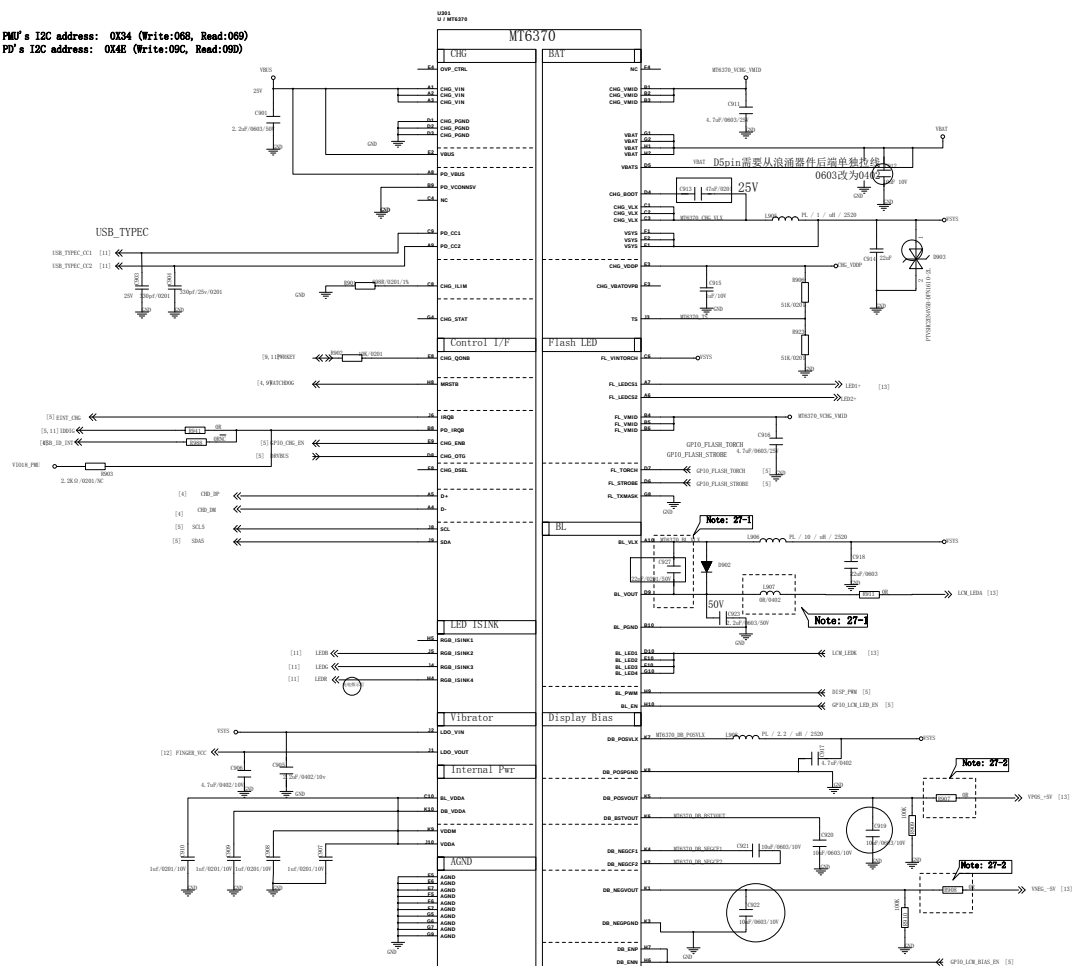
	HW GPIO configuration		Trapping Option		DRAM type	VDRAM2 Power source (VS2 LD01 ba11)
	AUD_SYNC_MISO	AUD_CLK_MISO	VDRAM1	VDRAM2		
	0	0	1.125V	0.6V	LP4X	VDRAM1
	0	1	OFF	1.8V	LP4X (Ext x 2 EN)	VS1
	1	0	1.225V	OFF	LP3	VDRAM1
	1	1	1.125V	1.8V	LP4X (Ext x 1 EN)	VS1



Schematic design notice of "22_POWER_MT6358-General"

Note 22-1: EXT_PMIC_EN1 : For UFS_1V8, and keep floating if it is not used
EXT_PMIC_EN2 : For VA09 of SSUSB/UFS, and keep floating if it is not used

MT6370 PMU's I2C address: 0X34 (Write:068, Read:069)
MT6370 PD's I2C address: 0X4E (Write:09C, Read:09D)

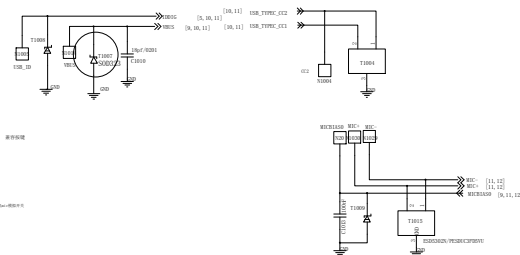
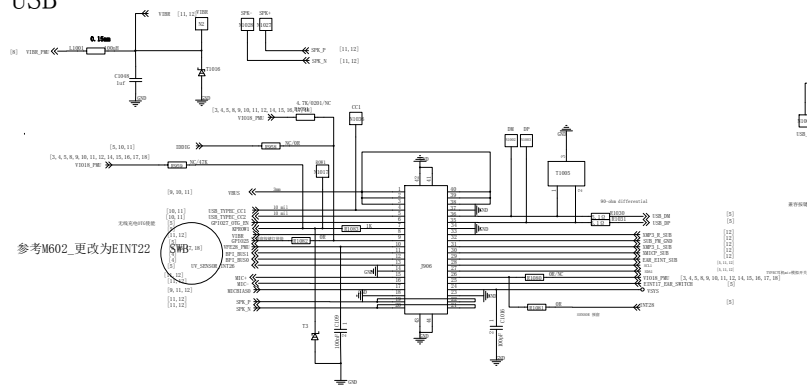


Schematic design notice of "27_POWER_SubPMIC-HV powers" page.

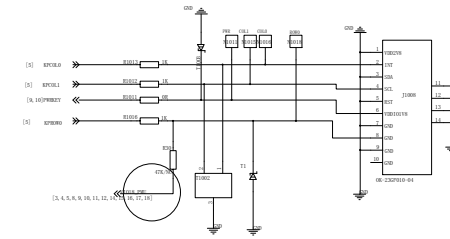
Note 27-1: It is recommended to reserve 0-ohm and cap. for BOM fine tune to minimize RF de-sense.

Note 27-2: It is recommended to reserve 0-ohm for BOM fine tune to minimize RF de-sense.

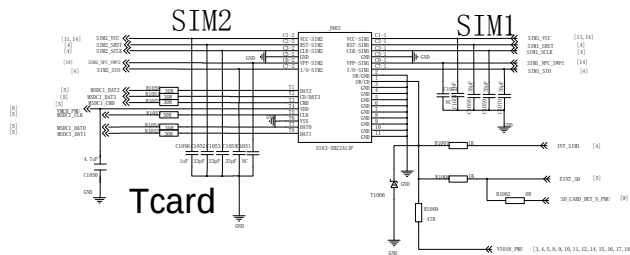
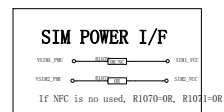
USB



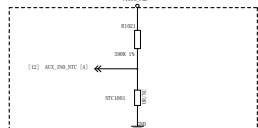
SIDE KEY



Nano sim1+ sim2&Tcard



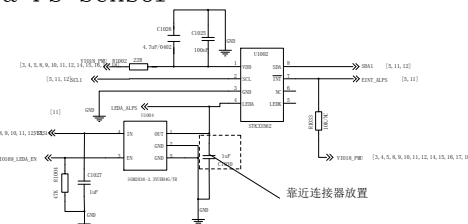
Thermistor / To sense board level temperature



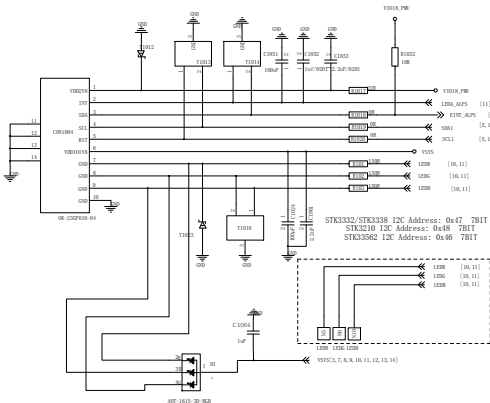
1. NTC100 must keep a distance about 6~8 mm away from AP and far from other heat sources 10 mm at least.
2. The distance is the shortest distance from package edge to edge.

Sensor

ALS & PS Sensor

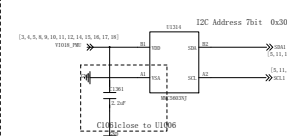


ALS & PS Sensor



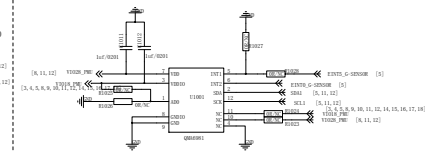
M-sensor1

Note: 77-1



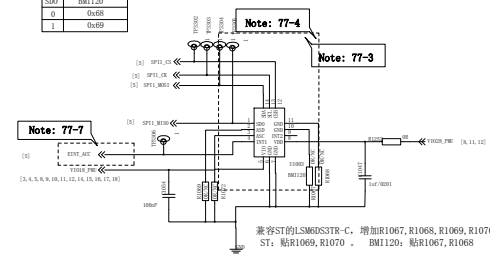
G-sensor

ADO	QMA6981	ADO	STE8BA53
0	0x12	7bit:	0x18
1	0x13		



G+Gyro sensor

SD0	EMI120
0	0x68
1	0x69



Schematic design notice of "77_PERI_SENSORS_MEMs_ALS/PS" page.

Note 77-1: [M sensor] Keep a minimum distance of 15mm from power ICs / PCB traces of more than 100mA / magnet component. Check HW design notice for more detail

Note 77-2: [A+G] For optimized GPS performance, please check HW design notice for Sensor selection guide

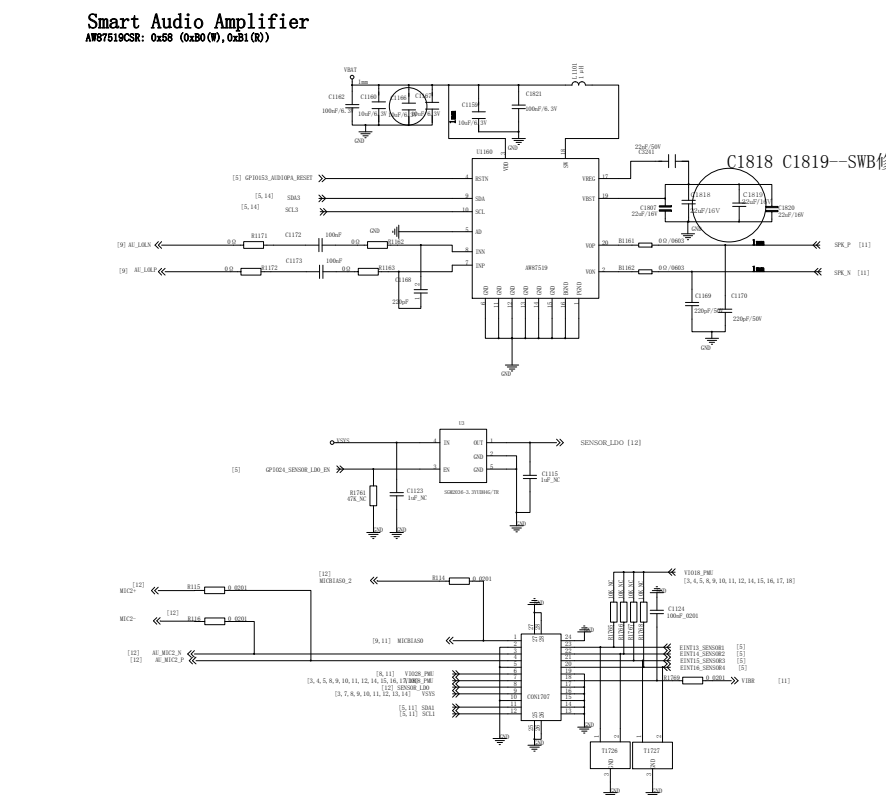
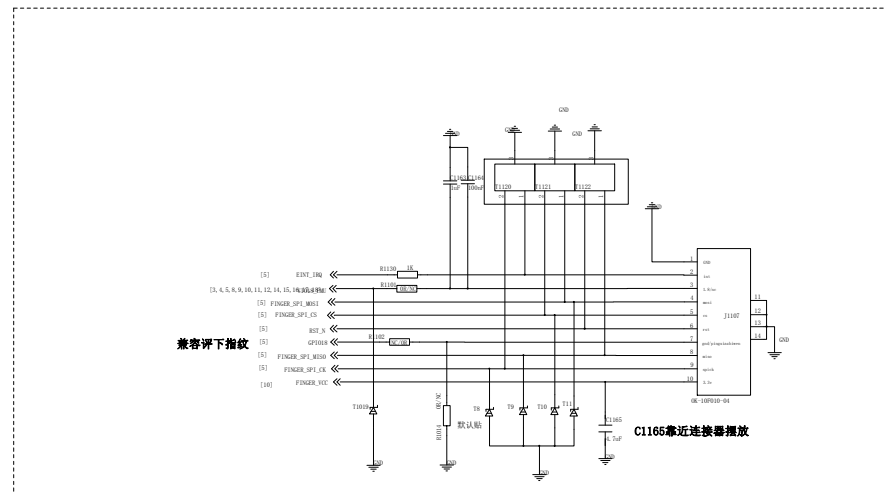
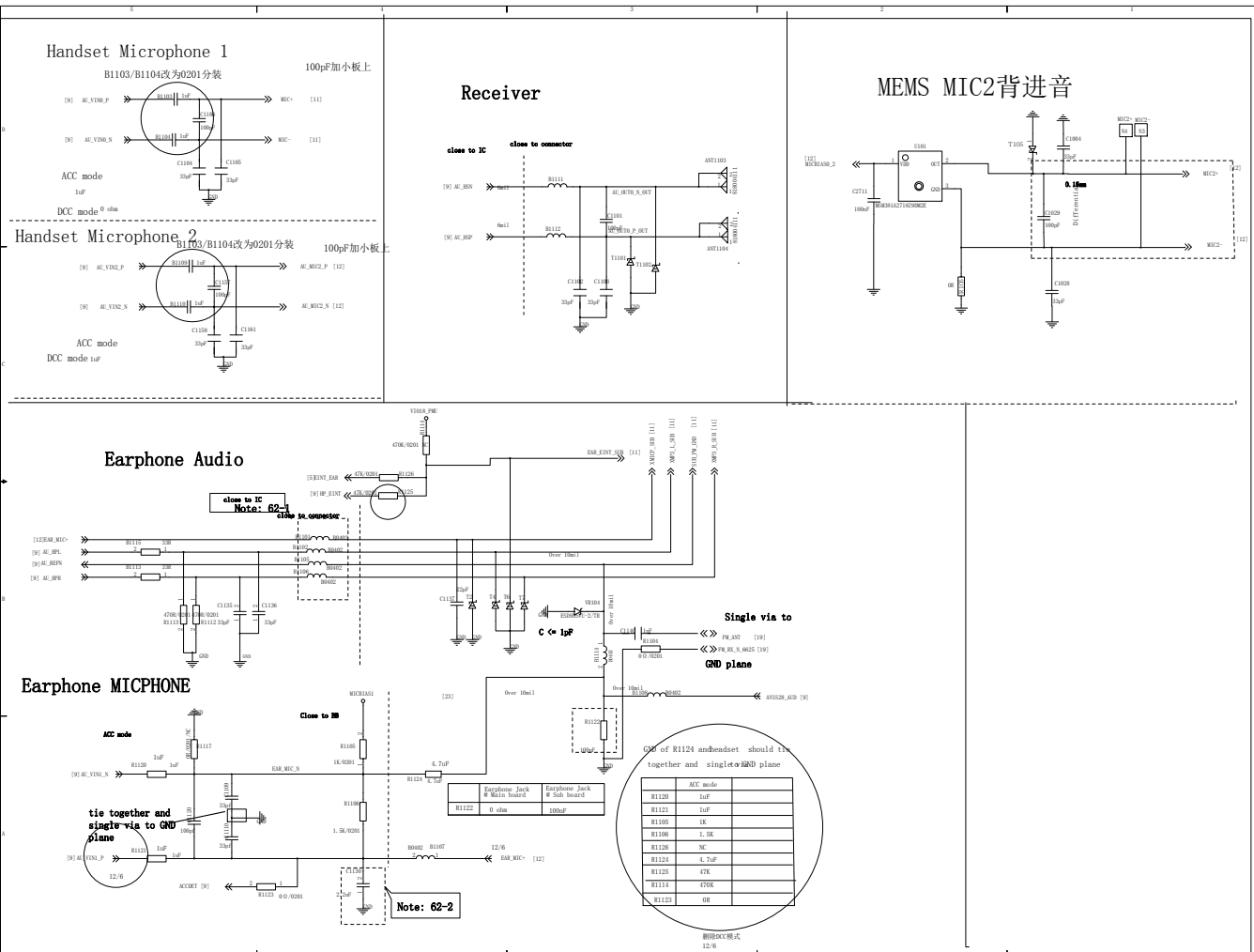
Note 77-3: [A+G] MUST use SPI for optimized sensor hub performance **DO NOT USE i2C**

Note 77-4: [A+G] Suggest choose sensor support FIFO watermark interrupt otherwise we cannot support Hifi-sensor, daydream VR. And Sensor-location accuracy will become worse.

Note 77-5: [Baro] Reserve Baro sensor for LPpe feautre (Must for North America Operator / NA SKU)

Note 77-6: DO NOT share Sensor hub i2C to other non-SCP device

Note 77-7: Interrupt pin of MEMS sensor must be assign to ball EINT[12:0]



Schematic design notice of "62_PERI_AUDIO_IO" page.

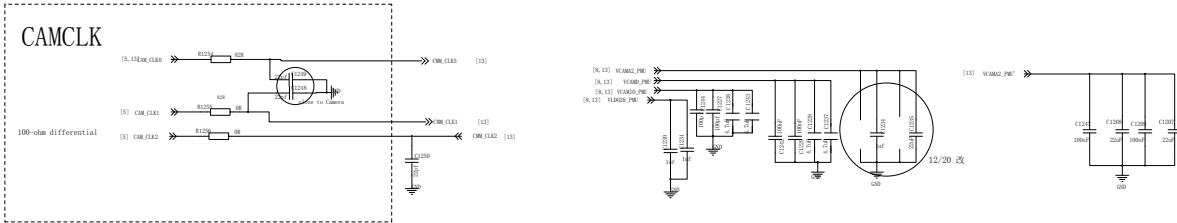
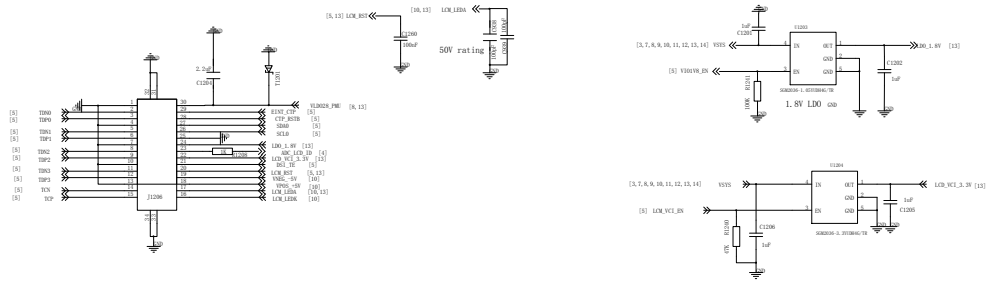
Note 62-1: Part of BEAD6202, BEAD6203, BEAD6204 and BEAD6205 needs changed to "BLM18BD102SN1" for high THD performance (-90dB) but this BOM change will results in FM RSSI 10dB degraded .

Note 62-2: Reserved Cap for CS/RS test, please double check multi-key function when used

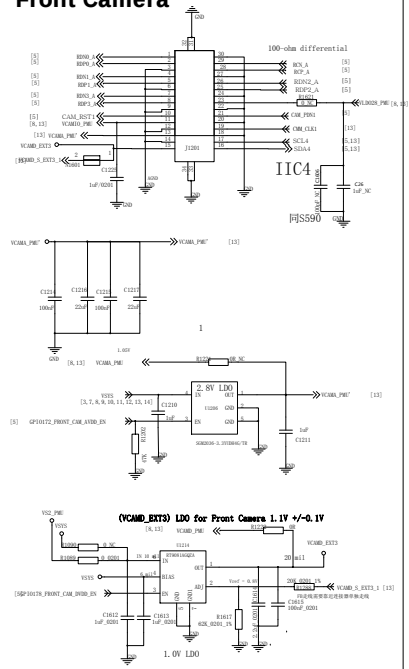
Note 62-3: For better ESD or surge performance we need choose suitable device for system protection. Please refer to [Surge device selection guide V2.0] provide by MTK.

Note 62-4:

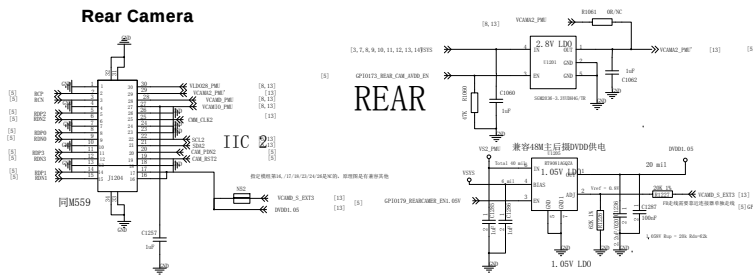
LCD



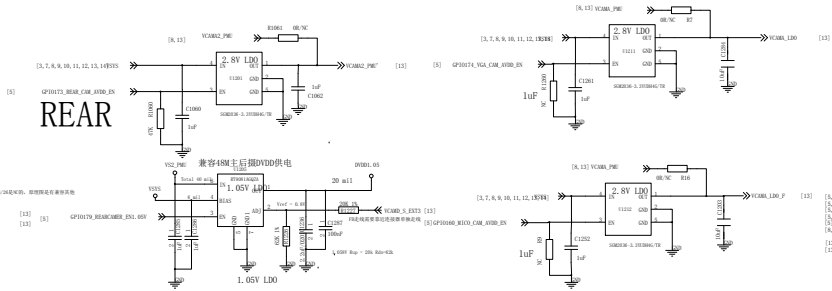
Front Camera



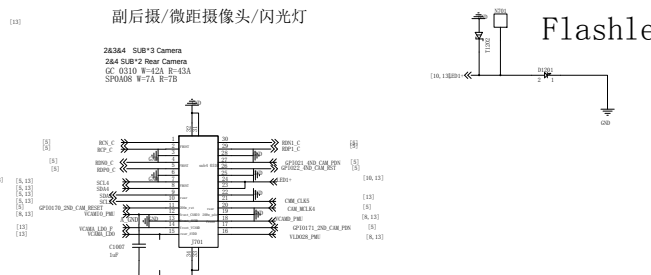
Rear Camera



REAR

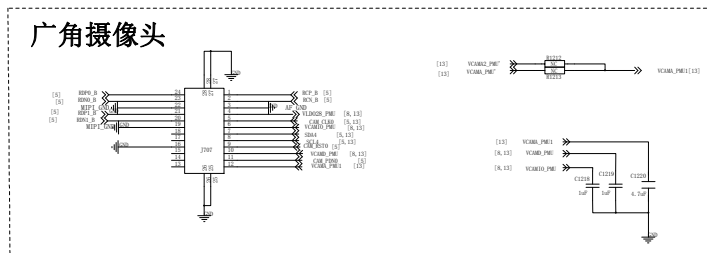


副后摄/微距摄像头/闪光灯

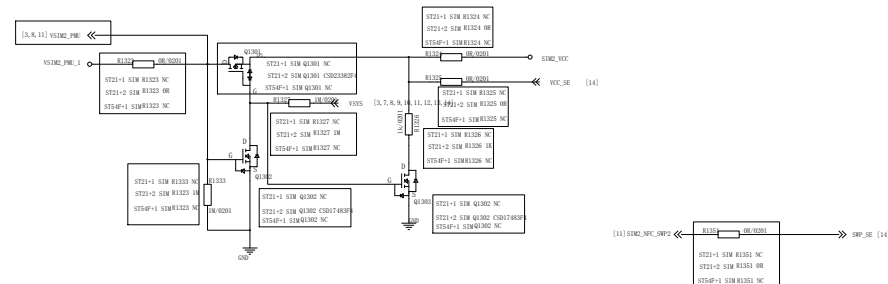


Flashled

广角摄像头

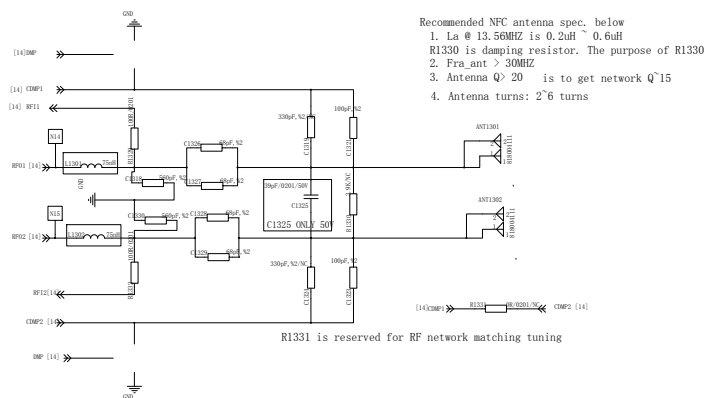


ST21 PIN ST54F, CAN NOT SUPPORT ST54H



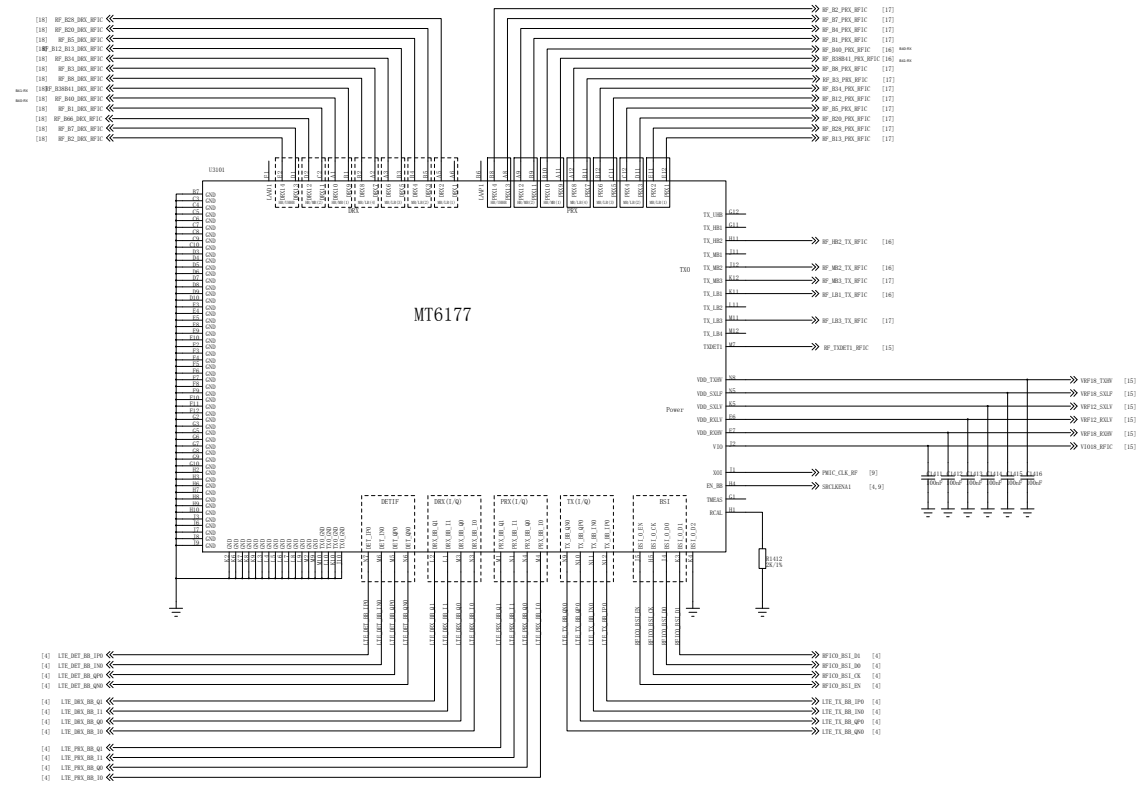
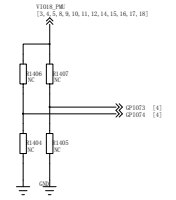
- SE ball name definition for ST54F, ST54H, and ST21NFCB, respectively

Ball	ST21NFC0	ST54F	ST54H
D3	NC	SE_SWP	NC
D4	NC	SE_SPI_MISO	SE_SPI_INT
D6	NC	SE_GND	SE_ISO_CLK
E3	NC	SE_SPI_SCK	SE_SPI_OUT(MISO)
E4	NC	SE_SPI_NSS	SE_SPI_NSS
E5	NC	SE_VCC	SE_SWP
E7	NC	NC	SE_SPI_SCK
E8	NC	SE_SPI_MOSI	SE_ISO_100
F4	NC	SE_ISO_RST	SE_ISO_RST
G2	NC	SE_ISO_100	SE_VCC
G3	NC	SE_ISO_CLK	SE_SPI_IN(MOSI)

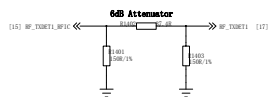


MT6177

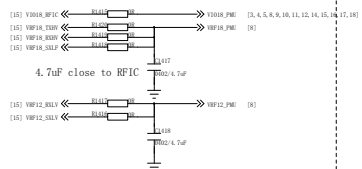
DRDI



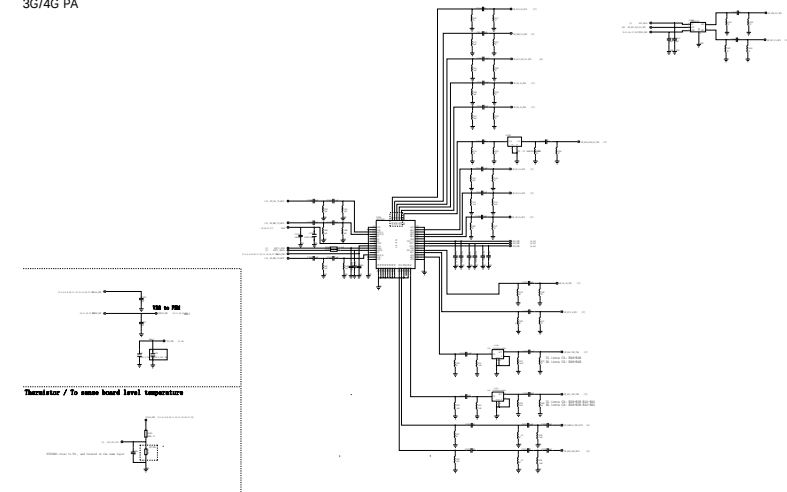
Attenuator for Detector



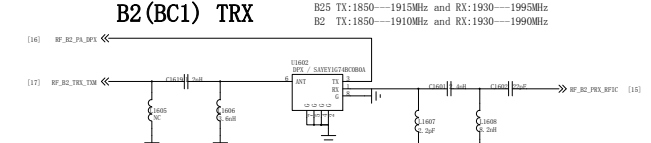
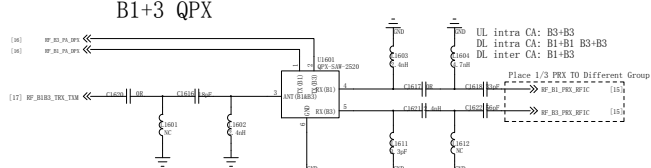
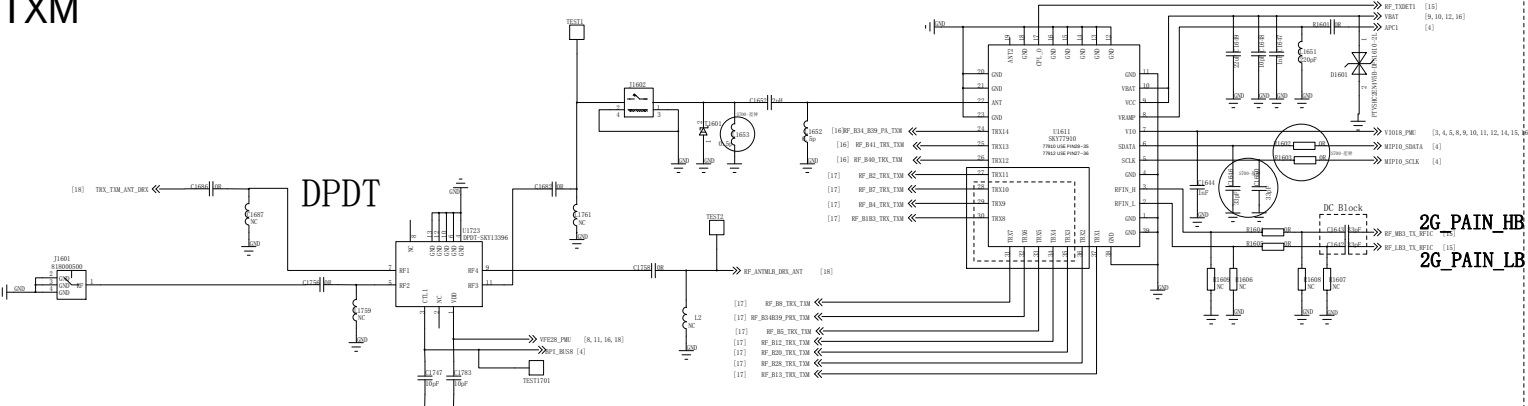
Power For MT6177



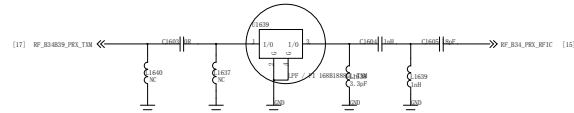
3G/4G PA



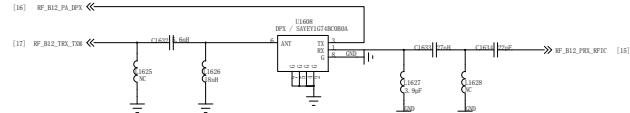
IXM



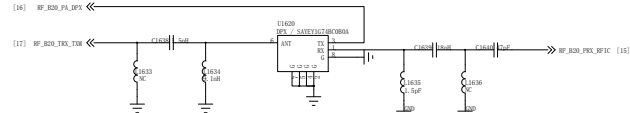
DCS1800/PCS1900/B34/B39 PRX



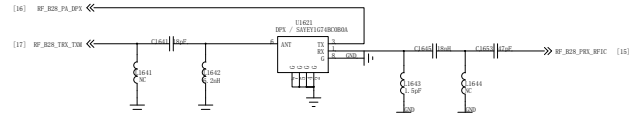
B12/17 TRX



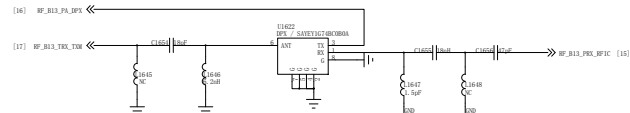
B20 TRX UL intra CA: B20+B20
DL intra CA: B20+B20



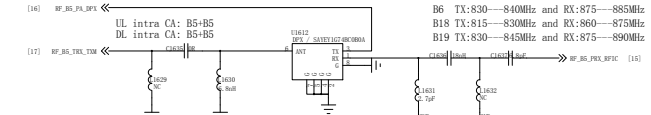
B28AB TRX



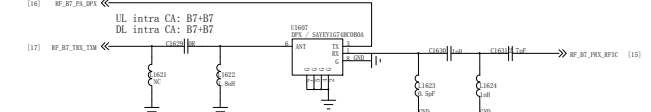
B13 TRX



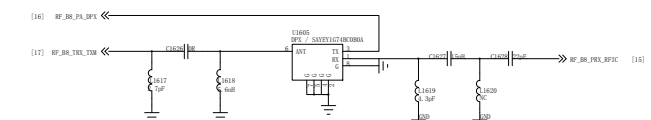
B5 (B6/B19/BC0) TRX



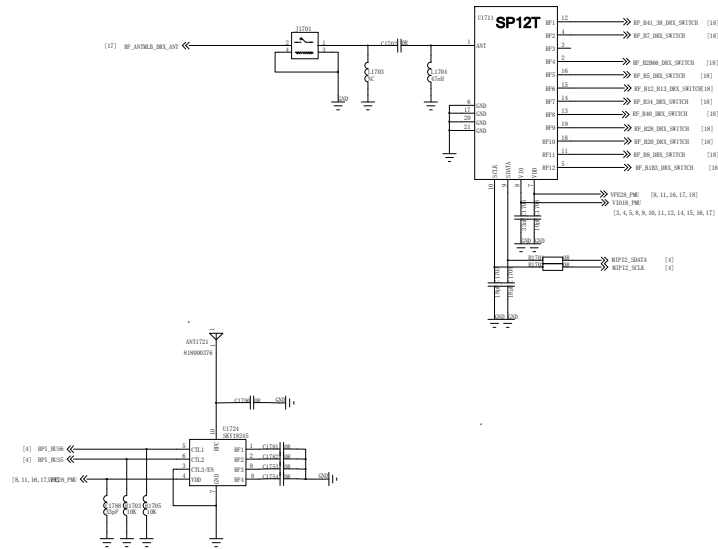
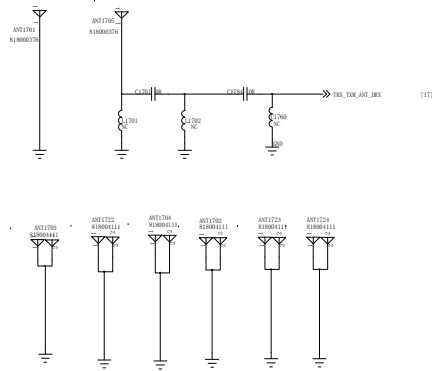
B7 TRX



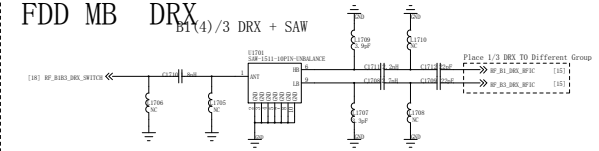
B8 TRX



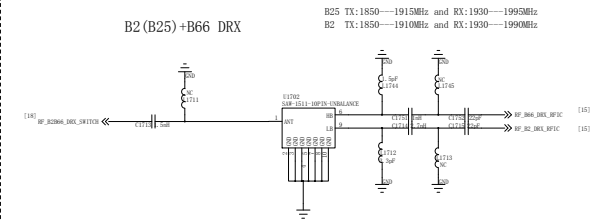
DRX ANT



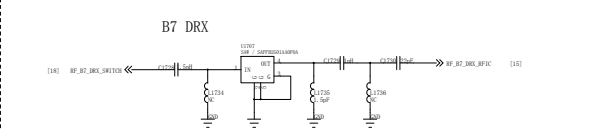
FDD MB DRX



B2 (B25) +B66 DRX

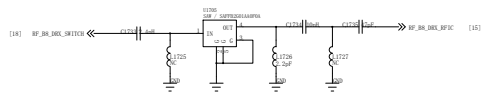


B7 DRX

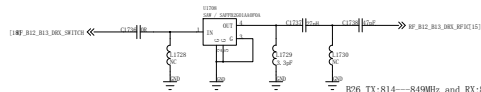


FDD LB DRX

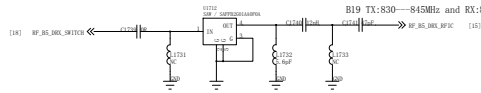
B8 DRX



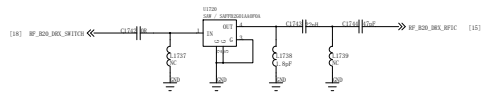
B12/13/17 DRX



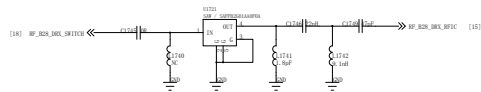
B5 (B6/B19/BC0) DRX



B20 DRX

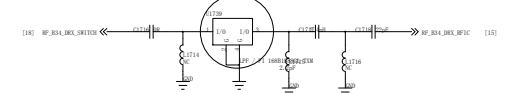


B28 DRX

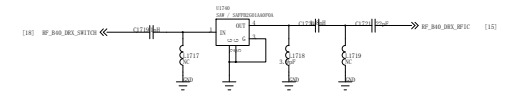


TDD MB DRX

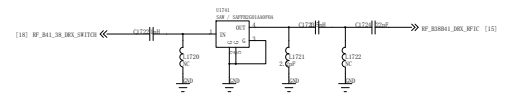
B34/39 DRX



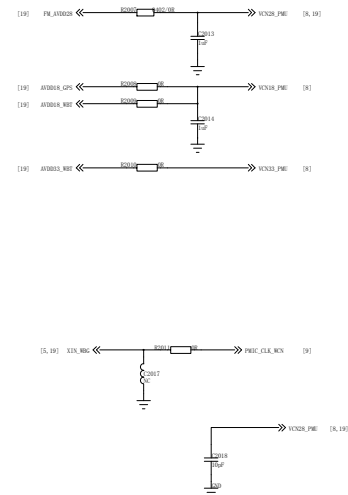
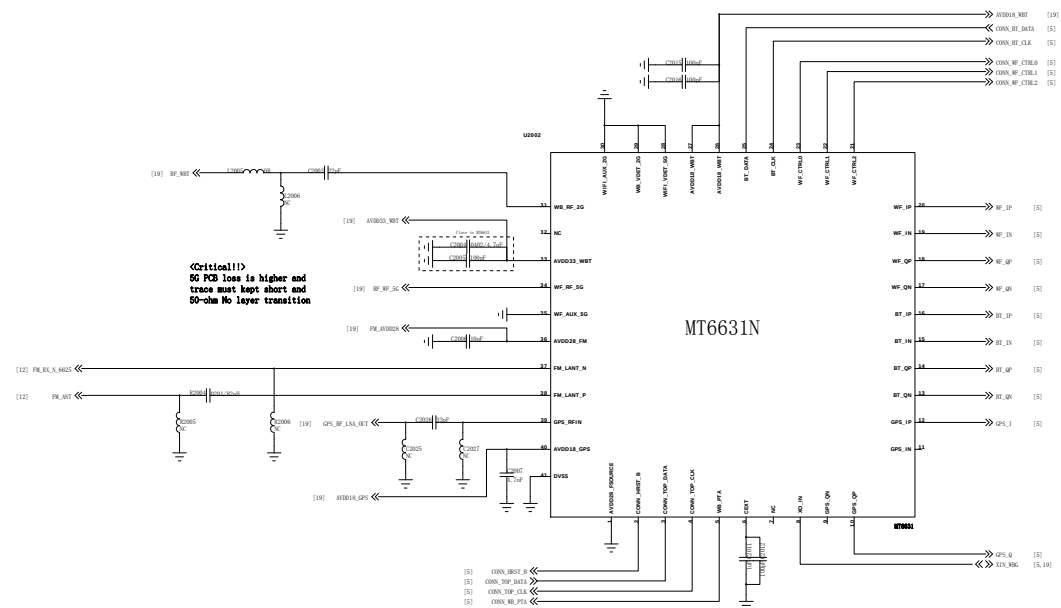
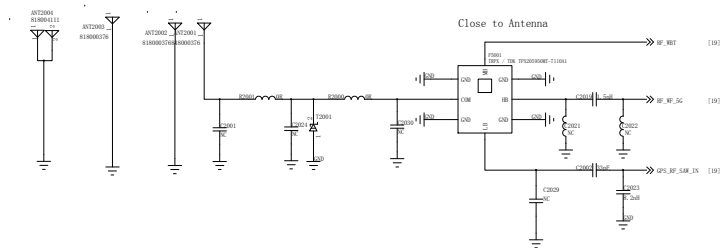
B40 DRX



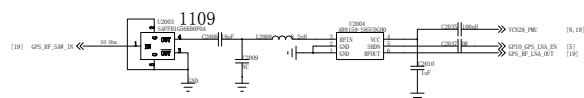
B38/41 DRX



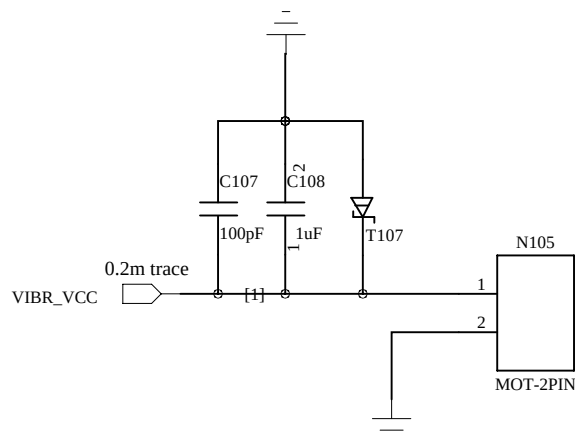
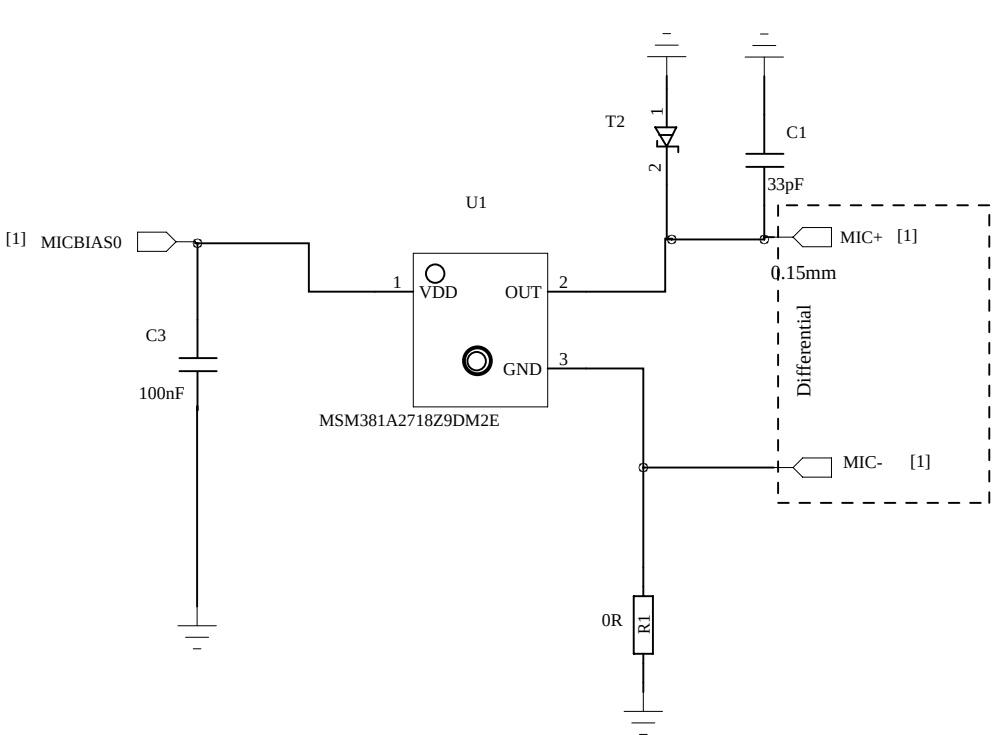
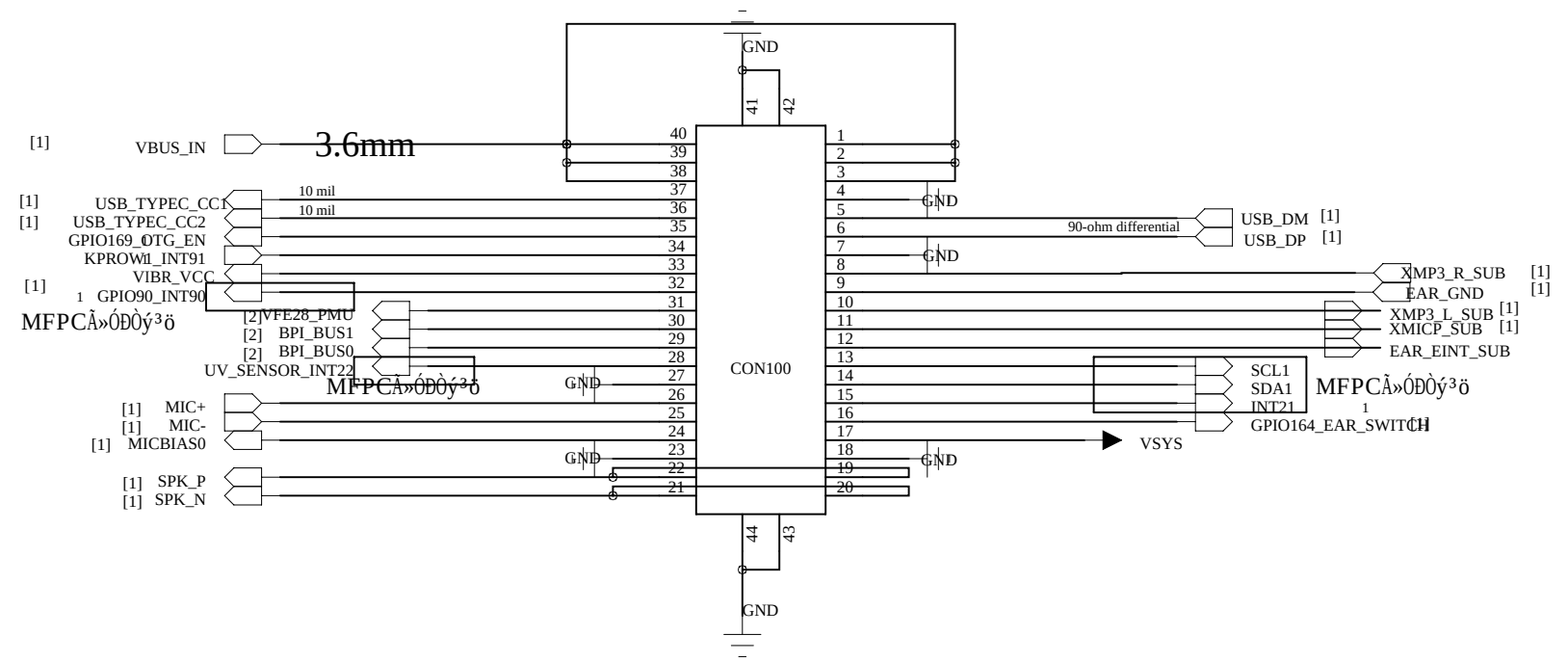
WCN-MT6331



Close to ANT

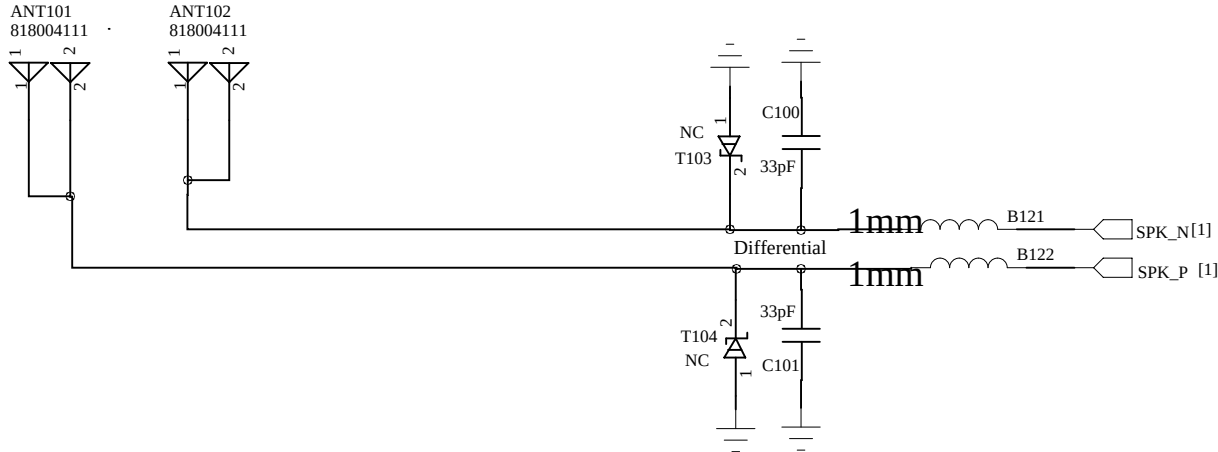


MEMS MIC

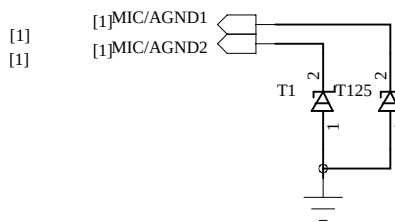
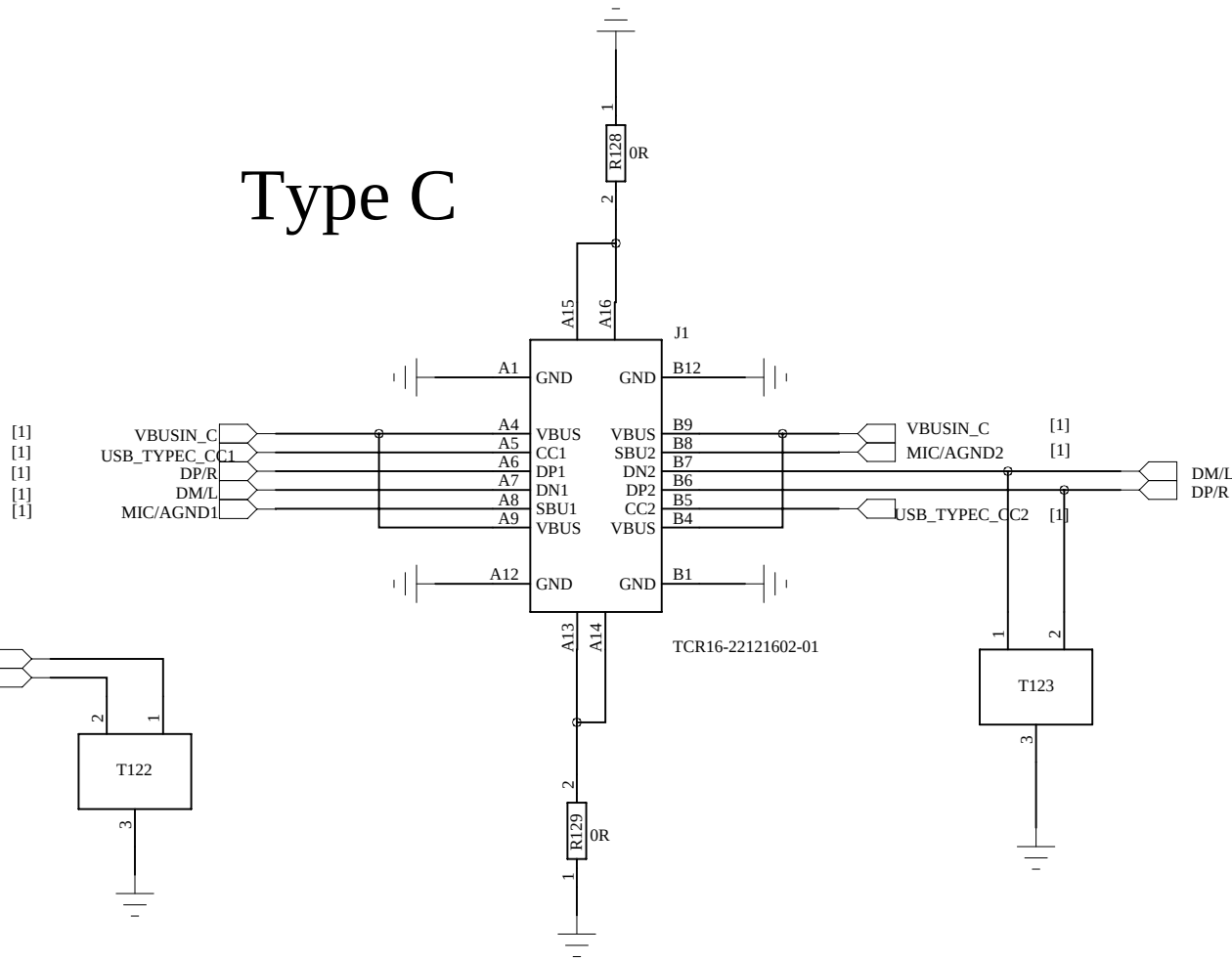


MOTOR

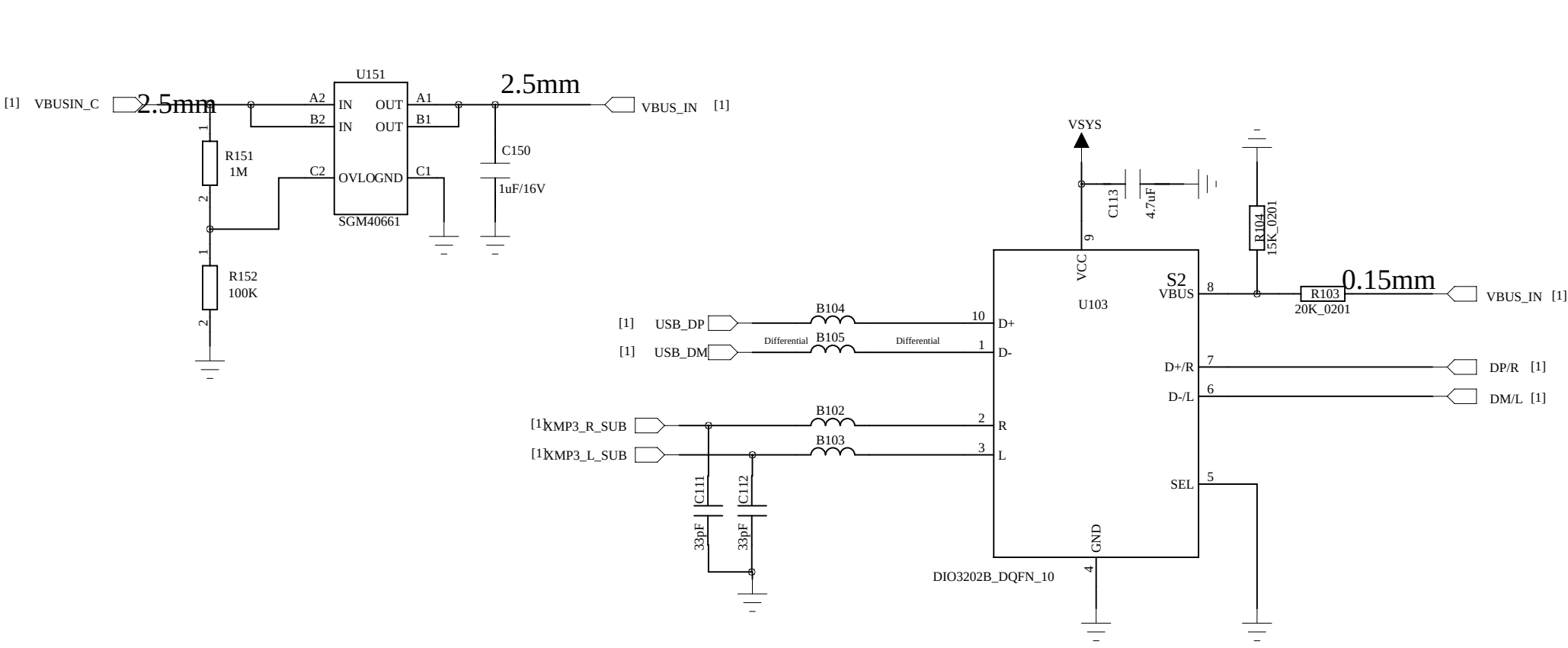
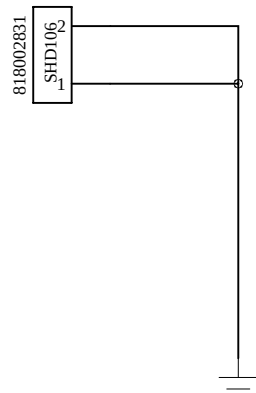
Speaker



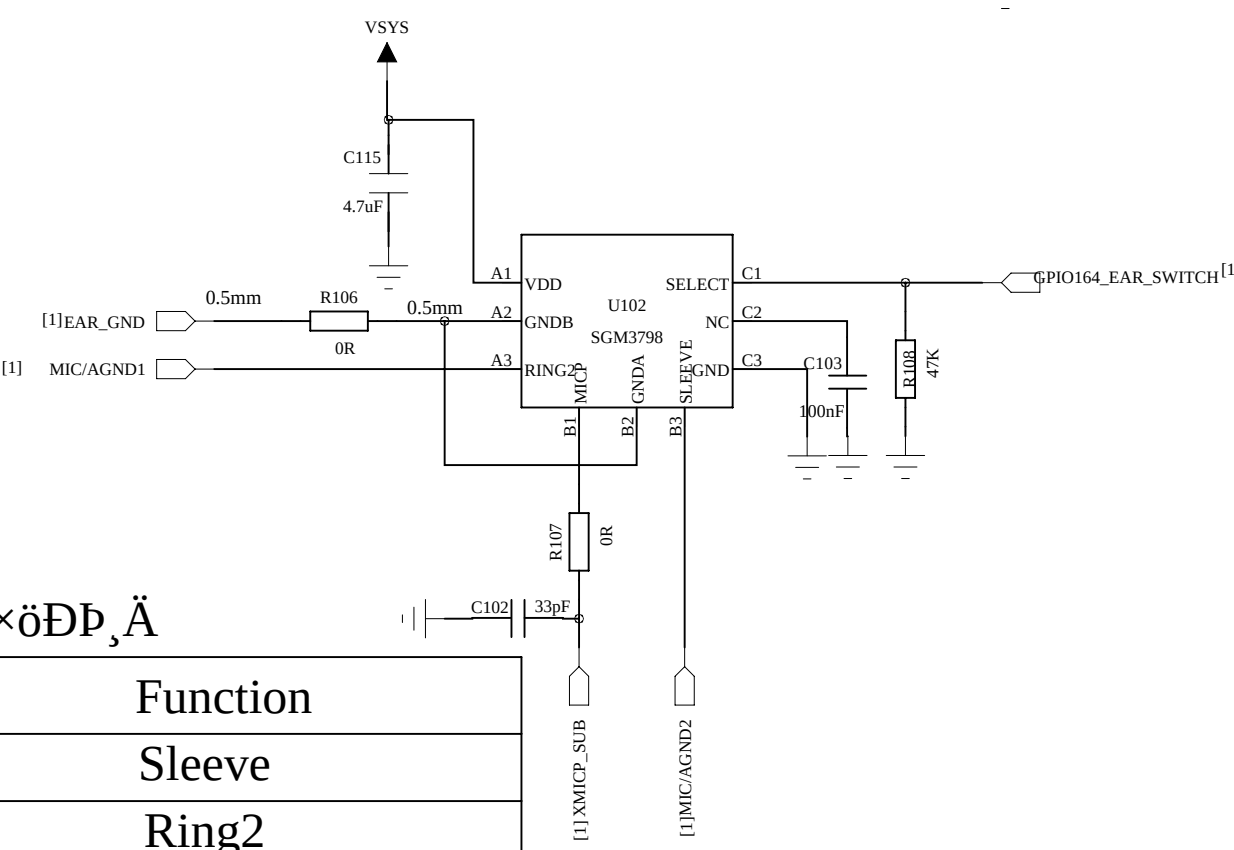
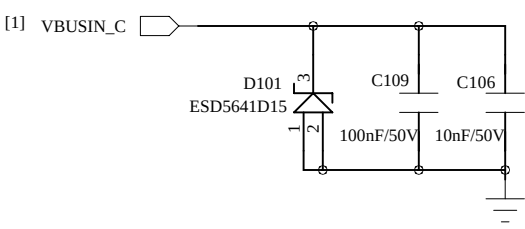
Type C



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Select Function

Select	Function
0	Sleeve
1	Ring2

